Absolute Maximum Ratings (Ta = 25°C)

	Characteristic		Symbol	Rating	Unit	
LED	Forward current Forward current derating (Ta \ge 53°C) Peak forward current (100 µs pulse, 100 pps) Power dissipation		lF	50	mA	
			ΔI _F / °C	-0.7	mA / °C	
			IFP	1	A	
			PD	100	mW	
	Power dissipation derating (Ta \geq 53°C)		ΔP _D /°C	-1.4	mW / °C	
	Reverse voltage		VR	5	V	\sum
	Junction temperature		Tj	125	$\left(\circ c \right)$	
	Off-state output terminal voltage		VDRM	600	\mathbb{V})
	On-state RMS current	Ta = 25°C Ta = 70°C	I _{T(RMS)}	100 50	mA	
	On–state current derating (Ta ≥ 25°C)		ΔI _T / °C	-1,1	mA/°C	
Detector	Peak on–state current (100μs pulse, 120 pps)	ITP	2	A		
	Peak nonrepetitive surge current (P _w = 10 ms)		ITSM	(/1.2)	Ą	\bigcirc
	Power dissipation Power dissipation derating (Ta \ge 25°C)		PD	300	mW	40
			ΔPD/°C	-4.0	mWℓ°℃	
	Junction temperature		Ř(/	115	°C)
Storag	Storage temperature range			-55 to 150	°C ∠	\mathcal{O}
Operating temperature range			Topr	–40 to 100 (()°¢	
Lead soldering temperature (10 s)			T _{sol}	260	°C	
Total package power dissipation			PT	330	mW	
Total package power dissipation derating $(Ta \ge 25^{\circ}C)$		ΔPτ/°C	4.4	mW / °C		
	on voltage D s., R.H.≤ 60 %)	(Note 1)	BVS	5000	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(Note 1) Device considered a two terminal device: Pins 1, 2 and 3 shorted together and pins 4 and 6 shorted together.

Recommended Operating Conditions

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	VAC	—	—	240	Vac
Forward current	IF*	15	20	25	mA
Peak on-state current	ITP	—	—	1	А
Operating temperature	T _{opr}	-25		85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

* In the case of TLP3062

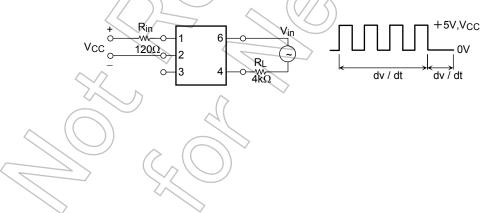
Individual Electrical Characteristics (Ta = 25°C)

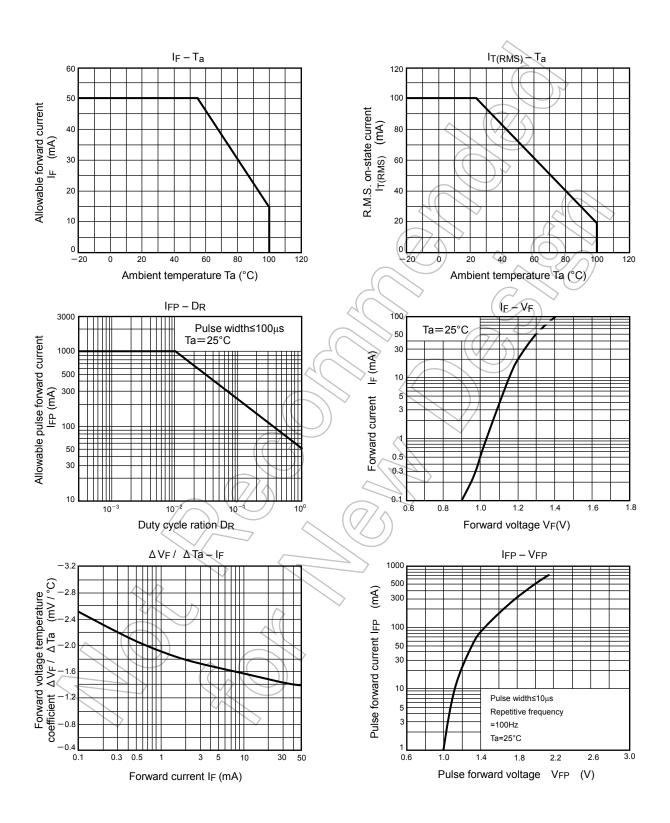
	Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
LED	Forward voltage	VF	I _F = 10 mA	1.0	1.15	1.3	V
	Reverse current	I _R	V _R = 5 V	_	_	10	μA
	Capacitance	Ст	V = 0 V, f = 1 MHz	/	10	_	pF
Detector	Peak off-state current	IDRM	V _{DRM} = 600 V		10	1000	nA
	Peak on-state voltage	V _{TM}	I _{TM} = 100 mA		1.7	3.0	V
	Holding current	lΗ	6	7(0.6	_	mA
	Critical rate of rise of off-state voltage	dv / dt	V _{in} = 240 Vrms, Ta = 85 °C (Fig.1)	200	500	_	V / μs
	Critical rate of rise of commutating voltage	dv / dt (c)	Vin = 60 Vrms, IT = 15 mA (Eig.1)	_	0.2	_	V / μs

Coupled Electrical Characteristics (Ta = 25°C)

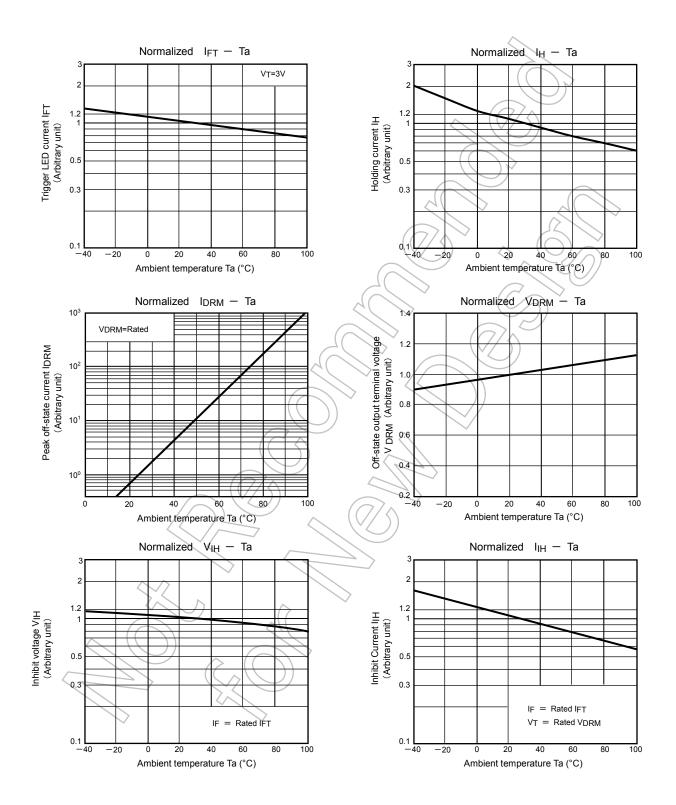
Characteristic		Symbol	Test Condition	Min	Typ.	Max.	Unit
	TLP3061(S)	IFT		\sim	, S	15	
Trigger LED current	TLP3062(S)		$V_T = 3V$		5	10	mA
	TLP3063(S)			\mathbb{R}^{2}	—	5	
Inhibit voltage		VIH	IF = rated IFT	<u> </u>	—	50	V
Leakage in inhibited state		Ін	IF = rated IFT VT = rated VDRM	_	100	300	μΑ
Capacitance input to output		es	V _S = 0 V, f = 1 MHz	-	0.8	_	pF
Isolation resistance		Rs	V _S = 500 V, R.H.≤ 60 %	5×10 ¹⁰	10 ¹⁴	—	Ω
Isolation voltage		BVs	AC, 60 s	5000	_	_	Vrms

dv / dt test circuit Fig. 1





NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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